



Welcome United States Patent and Trademark Office

☐ Search Results

BROWSE

SEARCH

IEEE XPLORE GUIDE

Results for "( ( ansys&lt;in&gt;metadata ) &lt;and&gt; ( temperature&lt;in&gt;metadata ) )&lt;and&gt; ( semicondu..."

Your search matched 13 of 1235066 documents.

☐ e-mail

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

## » Search Options

[View Session History](#)
[New Search](#)

## Modify Search

☐ Check to search only within this results set
Display Format: ☒ Citation ☐ Citation & Abstract

## » Key

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

## Select Article Information

- ☐ 1. **Temperature and stress distribution in the SOI structure during fabricatio**  
Cher Ming Tan; Zhenghao Gan; Xiaofang Gao;  
Semiconductor Manufacturing, IEEE Transactions on  
Volume 16, Issue 2, May 2003 Page(s):314 - 318  
Digital Object Identifier 10.1109/TSM.2003.811886  
[AbstractPlus](#) | [References](#) | Full Text: [PDF\(354 KB\)](#) IEEE JNL
- ☐ 2. **Thermal transient modeling and experimental validation in the European**  
Pape, H.; Schweitzer, D.; Janssen, J.H.J.; Morelli, A.; Villa, C.M.;  
Components and Packaging Technologies, IEEE Transactions on [see also Cc  
Packaging and Manufacturing Technology, Part A: Packaging Technologies, IE  
on]  
Volume 27, Issue 3, Sept. 2004 Page(s):530 - 538  
Digital Object Identifier 10.1109/TCAPT.2004.831791  
[AbstractPlus](#) | [References](#) | Full Text: [PDF\(1040 KB\)](#) IEEE JNL
- ☐ 3. **Crystal SiGeC far infrared sensor with temperature isolation improvemen**  
Ming-Chun Hsieh; Yean-Kuen Fang; Pei-Ming Wu; Wen-De Wang;  
Electronics Letters  
Volume 39, Issue 8, 17 April 2003 Page(s):656 - 658  
Digital Object Identifier 10.1049/el:20030442  
[AbstractPlus](#) | Full Text: [PDF\(344 KB\)](#) IEE JNL
- ☐ 4. **Anodic bonding of optical fibers to silicon for integrating MEMS based op**  
**and temperature sensors onto optical fibers**  
Saran, A.; Abeysinghe, D.C.; Deshmukh, P.; Flenniken, R.; Boyd, J.T.;  
TRANSDUCERS, Solid-State Sensors, Actuators and Microsystems, 12th Inter  
Conference on, 2003  
Volume 1, 8-12 June 2003 Page(s):564 - 567 vol.1  
[AbstractPlus](#) | Full Text: [PDF\(363 KB\)](#) IEEE CNF
- ☐ 5. **Predicting hysteretic oscillations in over-temperature protection of a pow**  
**transient electrothermal circuit simulation**  
Williams, R.K.; Sevilla, L.T.; Rodamaker, M.C.;  
Power Semiconductor Devices and ICs, 1993. ISPSD '93. Proceedings of the  
Symposium on  
18-20 May 1993 Page(s):304 - 309  
Digital Object Identifier 10.1109/ISPSD.1993.297143

**13. Double-Sided IPEM Cooling Using Miniature Heat Pipes**

Martens T. J. ; Nellis G. F. ; Pfotenhauer J. M. ; Jahns T. M. ;

IEEE Transactions on Components and Packaging Technologies : Accepted for publication

Volume PP, Issue 99, 2005 Page(s):1 - 10

Digital Object Identifier 10.1109/TCAPT.2005.848591

[AbstractPlus](#) | Full Text: [PDF](#)(1704 KB) IEEE JNL[Help](#) [Contact Us](#) [Privacy & :](#) 

© Copyright 2005 IEEE –

Indexed by

